3D CERAMIC INTERCONNECT DEVICES

Products & Applications

• 3D-circuit carriers for the packaging of sensors, chips, LED’s, MEMS
• For airborne electronics, photonic sensors, medical devices, antennas...

Technology

High precision 3D-components made of advanced ceramics (alumina and AlN)

Metal thin-film sputtering:

• For assembly technologies (soldering, bonding)
• Ti/Pt/Au, Cr/Ni/Au, NiCr/Au
• Silver, aluminium, indium...

High-selectivity laser ablation:

• Track width ≤ 50 μm (0.002“)
• Insulation width 50 μm min (0.002“)
• Tight tolerance down to 10 μm (0.0004“)

Benefits

• 3D packaging with electrical & mechanical functions
• Good electrical insulation
• High thermal conductivity
• High dimensional stability
• Flexible process from prototypes to medium-size production batches
• No expensive tooling